



# Material Composition Declaration

## EPC2218A

Company Name	Efficient Power Conversion (EPC)	Issue Date:	1/10/2023
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	10.2 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	7.8722	76.8435	80.0989	768435
	Silicon oxide	7631-86-9	0.0506	0.4942		4942
	Silicon nitride	12033-89-5	0.0147	0.1435		1435
	Gallium nitride	25617-97-4	0.0392	0.3828		3828
	Aluminum	7429-90-5	0.0773	0.7545		7545
	Aluminum nitride	24304-00-5	0.0083	0.0812		812
	Titanium	7440-32-6	0.0016	0.0159		159
	Titanium nitride	25583-20-4	0.0742	0.7240		7240
	Copper	7440-50-8	0.0013	0.0126		126
	Tungsten	7440-33-7	0.0084	0.0820		820
	Polyimide		0.0578	0.5646	5646	
Under Bump Metal	Titanium	7440-32-6	0.0013	0.0127	0.1390	127
	Copper	7440-50-8	0.0129	0.1263		1263
Solder Bump	Copper	7440-50-8	0.1294	1.2628	19.7622	12628
	Nickel	7440-02-0	0.0772	0.7533		7533
	Tin	7440-31-5	1.7853	17.4267		174267
	Silver	7440-22-4	0.0327	0.3194		3194
Sum in total:			10.2444	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.